

Tongsi Industrial - Product Parameter Table

Category	Product Type / Model	Surface Treatment	Material Options	Application / Process	Key Features / Notes
Power Module PIN	Various Types	Overall Gold Plating, Overall Tin Plating, Ternary Plating, Selective Plating, Semi-Plating, Partial Plating	H65, H68, C1100, C68350, C5100, C5440, C14500, C2700, C70250, C19400, C18150, C10200, C3604 (Leaded)	Soft Soldering, Solder Paste Reflow, Ultrasonic Welding. For Automotive HPD Module Series	Stringent quality control, 100% performance testing.
Ultrasonic Welding PIN	One-piece Needle (Holder+Pin)	Half Gold Plated (0.2-1.5 μ "), Half Tin Plated (Optional)	Pin: C5100, Base: Oxygen-Free Copper	Ultrasonic Welding	For high-precision welding requirements.
Holder Series	Work Type, T-base (Through-hole, Blind-hole Step)	Overall Gold Plating (0.2-1.5 μ "), Tin Plating, or Bare Copper	C1100, H65, C68350, C5100, C5440, C14500	Solder Paste, Tin Sheet, Ultrasonic Welding	Customizable base materials.
Power Module PIN	T-shaped (Through-hole or Blind-hole step) Square Pin	Overall Gold Plated (0.2-1.5 μ "), Holder can be Tin Plated or Bare Copper	Base: C1100, H65, C68350, C5100, C5440, C14500; Pin: H65, C2700,	Soft Soldering, Solder Paste, Ultrasonic Welding, Laser Welding	Applicable to automotive-spec Drive (HPD) module series.
Power Module PIN	Extended Copper Ring Pins	Overall Gold Plated (0.2-1.5 μ ") or Tin Plated	Brass, Phosphor Bronze, Copper-Nickel-Silicon, Iron Bronze	Allows two different pins in one DBC, multi-layer fit.	Customizable for specific layout needs.
Power Module PIN	S-type Round Pin Terminals (0.8/1.0mm)	Overall Gold Plating (0.2-1.5 μ ") Overall Tin Plating Optional	Base: H65, H68, C1100, C68350, C5100, C5440, C14500; Pin: H65, C2700,	Soft Soldering, Solder Paste Pads, Ultrasonic Welding	Applicable to automotive-spec Drive (HPD) module series.
Power Module PIN	One-piece Straight Pin	Overall Gold Plating (0.2-1.5 μ ") or Tin Plating	T1, T2, C68350, C5100, C5440, C14500	Standard pin for various connections.	Simple and reliable design.
Press-Fit Pin	Press-Fit Pin (T-Flat, T-shaped fully plated)	Customizable	Pin: C5100; Base: C1100, H65, C68350, C5100, C5440, C14500	Press-Fit (Solderless Crimping), Soft Soldering, Solder Paste, Ultrasonic Welding	Applicable to automotive-spec Drive (HPD) module series.

Power Module PIN	Continuous Needle-shaped	Overall Gold Plated (0.2-1.5 $\mu\mu$ ") or Tin Plated	Brass, Phosphor Bronze, Copper-Nickel-Silicon, Iron Bronze	Smart Grid, Rail Transportation, Energy Storage, Charging, High-Power Supplies, Power Modules	Customizable length and plating.
Power Module Clip	Gold-Plated Clip, Bare Copper Clip	Bare Copper, Overall Gold Plated	TU1, TU2, T1, T2, C1100, CMC	Silicon Carbide High-Power Modules (Clip Bonding)	Increases operating efficiency by more than 10x compared to multi-wire bonding.
Power Module Cu Cell	Cylindrical, Square	Copper Protection	TU1, TU2, T1, T2, C1100	New Energy Vehicle Electric Drive Power Module (Traction Inverter)	Structural component for improved heat dissipation and electrical performance.
Signal Terminal	Various Types	Customizable based on requirements	Copper-based materials	Signal Transmission Interface	High reliability, low impedance.
Power Terminal	Various Types	Customizable based on requirements	Copper-based materials	High Current Transmission	High current capacity, high temperature resistance.
Retaining Ring	Various Types	Customizable based on requirements	Metal/Insulating Materials	Module Fixing and Insulation	Improves module mechanical stability.